

MOSFET - N-Channel, UniFET™

500 V, 28 A, 155 mΩ

FDA28N50

Description

UniFET MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on–state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

Features

- $R_{DS(on)} = 122 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V}, I_D = 14 \text{ A}$
- Low Gate Charge (Typ. 80 nC)
- Low Crss (Typ. 42 pF)
- 100% Avalanche Tested
- This Device is Pb-Free Halide, Free and RoHS Compliant

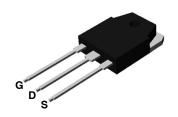
Applications

- PDP TV
- Uninterruptible Power Supply
- AC-DC Power Supply

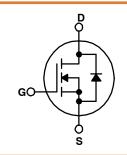
MOSFET MAXIMUM RATINGS (T_C = 25°C unless otherwise noted.)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	500	V
V _{GSS}	Gate to Source Voltage	±30	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	28 17	Α
I _{DM}	Drain Current - Pulsed (Note 1)	112	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	2391	mJ
I _{AR}	Avalanche Current (Note 1)	28	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)	31	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5	V/ns
P _D	Power Dissipation – (T _C = 25°C) – Derate Above 25°C	310 2.5	W W/°C
T _J ,T _{STG}	Operating and Storage Temperature Range	-55 to +175	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds		°C

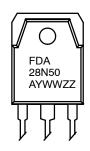
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-3P-3L CASE 340BZ



MARKING DIAGRAM



FDA28N50 A

YWW

77

Specific Device CodeAssembly Location

= Assembly Location = Date Code (Year and Week)

= Assembly Lot Code

ORDERING INFORMATION

Device	Package	Shipping [†]
FDA28N50	TO-3P-3L (Pb-Free)	450 Units / Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	0.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

$\frac{BV_{DSS}}{BV_{DSS}} \\ \frac{\Delta BV_{DSS}}{\Delta T_{J}} \\ \\ I_{DSS}$	teristics Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current	I_D = 250 μA, V_{GS} = 0 V, T_J = 25°C I_D = 250 μA, Referenced to 25°C	500	_	_	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	<u> </u>	+	-	_	\/
ΔT _J	Coefficient	I_D = 250 μ A, Referenced to 25°C	_			V
I _{DSS}	Zero Gate Voltage Drain Current			0.59	-	V/°C
	5	V _{DS} = 500 V, V _{GS} = 0 V	-	-	1	μΑ
		V _{DS} = 400 V, T _C = 125°C	_	-	10	
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	-	±100	nA
On Charac	teristics		•		•	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 14 A	_	0.122	0.155	Ω
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 14 A	_	34	_	S
Dynamic C	haracteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	3866	5140	pF
C _{oss}	Output Capacitance		-	576	766	pF
C_{rss}	Reverse Transfer Capacitance		-	42	63	pF
Q _{g(tot)}	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, I_D = 28 \text{ A},$	-	80	105	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V (Note 4)	-	21	_	nC
Q_{gd}	Gate to Drain "Miller" Charge		_	32	_	nC
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V_{DD} = 250 V, I_{D} = 28 A, V_{GS} = 10 V R_{G} = 25 Ω (Note 4)	-	56	122	ns
t _r	Turn-On Rise Time		-	126	262	ns
t _{d(off)}	Turn-Off Delay Time		-	210	430	ns
t _f	Turn-Off Fall Time		_	110	230	ns
Drain-Sou	rce Diode Characteristics and Maximum I	Ratings				
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	28	Α
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	112	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 20 A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 20 A,	_	530	_	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	8	_	μС

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. Repetitive Rating: Pulse–width limited by maximum junction temperature.
 2. L = 6.1 mH, I_{AS} = 28 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C.
 3. $I_{SD} \le 28$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, starting T_{J} = 25°C.
 4. Essentially independent of operating temperature typical Characteristics.

TYPICAL CHARACTERISTICS

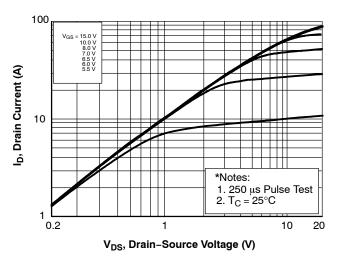


Figure 1. On-Region Characteristics

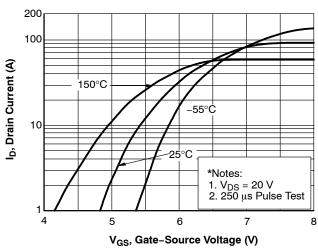


Figure 2. Transfer Characteristics

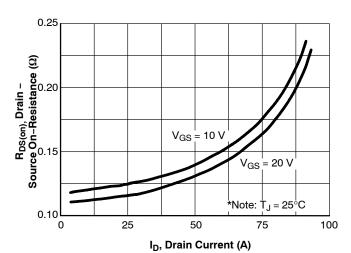


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

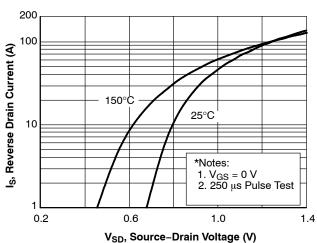


Figure 4. Body Diode Forward Voltage Variation vs Source Current and Temperature

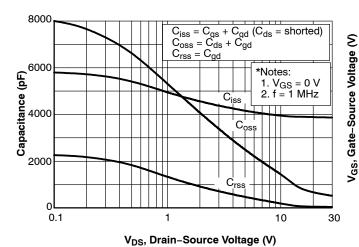


Figure 5. Capacitance Characteristics

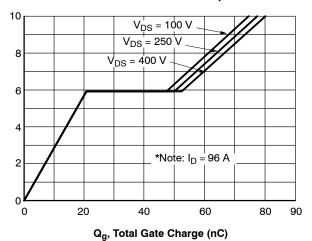
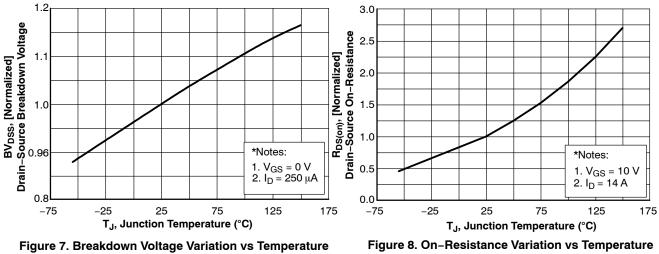


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS (CONTINUED)



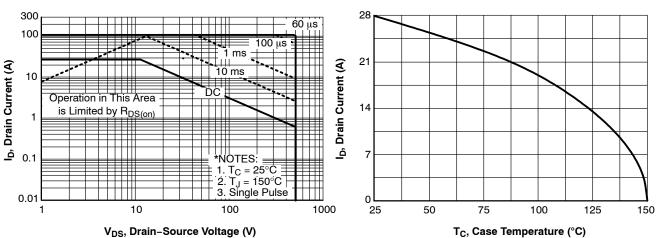
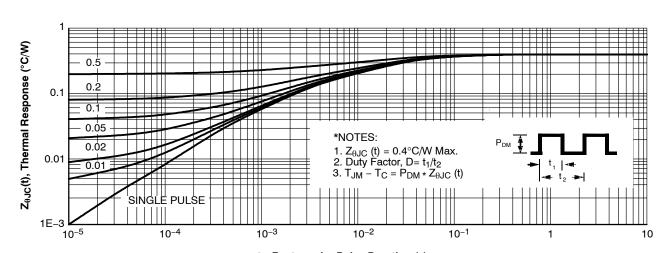


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature



t₁, Rectangular Pulse Duration (s)

Figure 11. Transient Thermal Response Curve

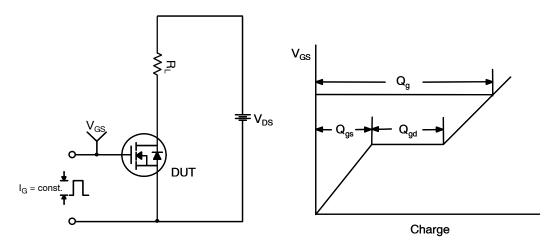


Figure 12. Gate Charge Test Circuit & Waveform

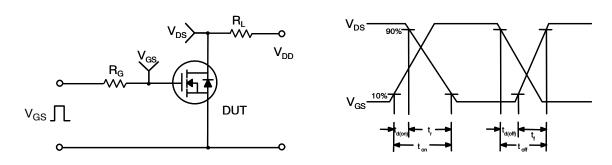


Figure 13. Resistive Switching Test Circuit & Waveforms

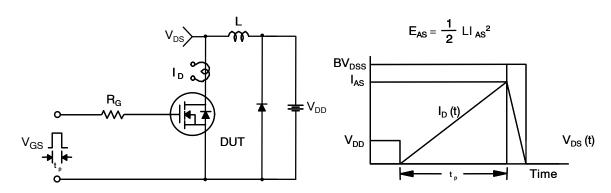
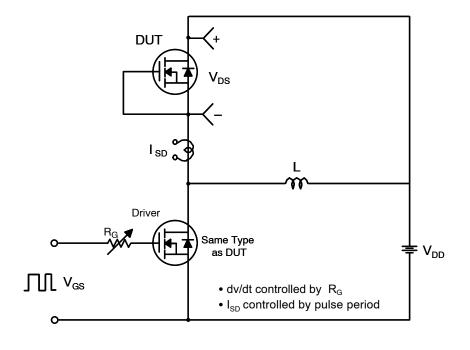


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



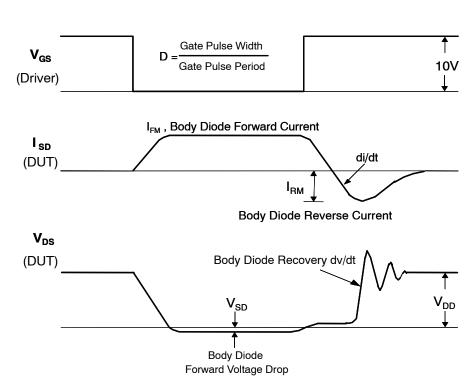
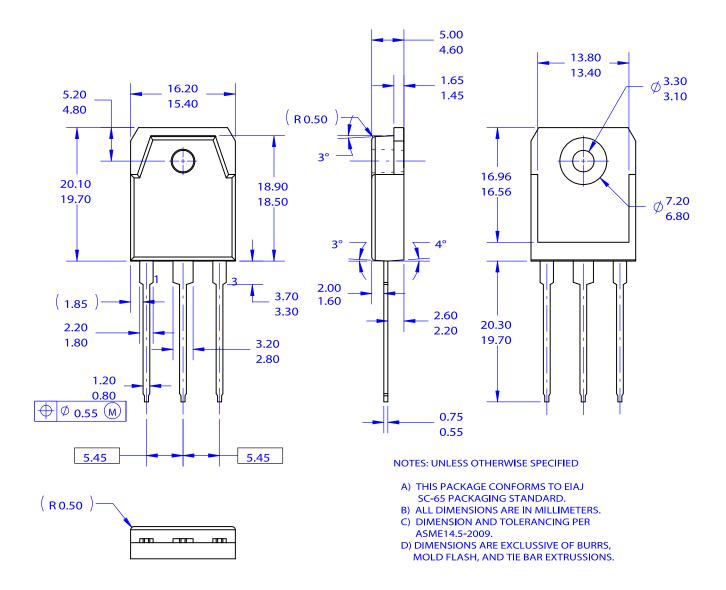


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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TO-3P-3LD / EIAJ SC-65, ISOLATED CASE 340BZ ISSUE O

DATE 31 OCT 2016



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